

Notice of References CitedApplication No.
08/988,246Applicant(s)
Sebastien et alExaminer
Rudy ZervigonGroup Art Unit
1763

Page 1 of 1

U.S. PATENT DOCUMENTS

	DOCUMENT NO.	DATE	NAME	CLASS	SUBCLASS
A	5,474,648	12/12/95	Patrick et al	156	627.1
B	5,366,585	11/22/94	Robertson et al	156	643
C	4,500,408	2/19/85	Boys et al	204	298
D	4,695,700	9/22/87	Provence et al	219	121PD
E					
F					
G					
H					
I					
J					
K					
L					
M					

FOREIGN PATENT DOCUMENTS

	DOCUMENT NO.	DATE	COUNTRY	NAME	CLASS	SUBCLASS
N						
O						
P						
Q						
R						
S						
T						

NON-PATENT DOCUMENTS

	DOCUMENT (Including Author, Title, Source, and Pertinent Pages)	DATE
U	E. van de Ven et al., "Advantages of Dual Frequency PECVD for Deposition of ILD and Passivation Films", 7th Int. IEEE VLSI Multilevel Interconnection Conference, June 12-13, 1990, Santa Clara, CA (June 1990)	6/90
V	Fitzgerald, A.E., Higginbotham, D.E., Grabel, A., Basic Electrical Engineering, McGraw Hill, 5th Ed., pp.132-134.	1981
W		
X		